

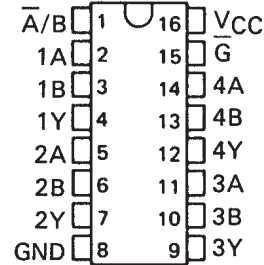
SN54LS257B, SN54LS258B, SN54S257, SN54S258 SN74LS257B, SN74LS258B, SN74S257, SN74S258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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- Three-State Outputs Interface Directly with System Bus
- 'LS257B and 'LS258B Offer Three Times the Sink-Current Capability of the Original 'LS257 and 'LS258
- Same Pin Assignments as SN54LS157, SN74LS157, SN54S157, SN74S157, and SN54LS158, SN74LS158, SN54S158, SN74S158
- Provides Bus Interface from Multiple Sources in High-Performance Systems

SN54LS257B, SN54S257,
SN54LS258B, SN54S258 . . . J OR W PACKAGE
SN74LS257B, SN74S257,
SN74LS258B, SN74S258 . . . D OR N PACKAGE

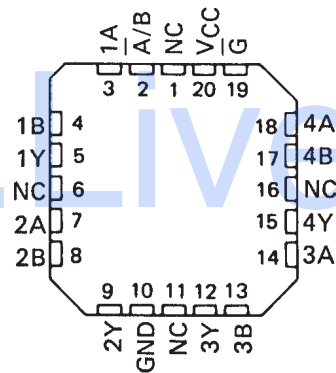
(TOP VIEW)



	AVERAGE PROPAGATION DELAY FROM DATA INPUT	TYPICAL POWER DISSIPATION†
'LS257B	9 ns	55 mW
'LS258B	9 ns	55 mW
'S257	4.8 ns	320 mW
'S258	4 ns	280 mW

SN54LS257B, SN54S257,
SN54LS258B, SN54S258 . . . FK PACKAGE

(TOP VIEW)



† Off state (worst case)
description

These devices are designed to multiplex signals from four-bit data sources to four-output data lines in bus-organized systems. The 3-state outputs will not load the data lines when the output control pin (\bar{G}) is at a high-logic level.

Series 54LS and 54S are characterized for operation over the full military temperature range of -55°C to 125°C ; Series 74LS and 74S are characterized for operation from 0°C to 70°C .

NC-No internal connection.

FUNCTION TABLE

OUTPUT CONTROL	INPUTS		OUTPUT Y		
	SELECT	A	B	'LS257B 'S257	'LS258B 'S258
H	X	X	X	Z	Z
L	L	L	X	L	H
L	L	H	X	H	L
L	H	X	L	L	H
L	H	X	H	H	L

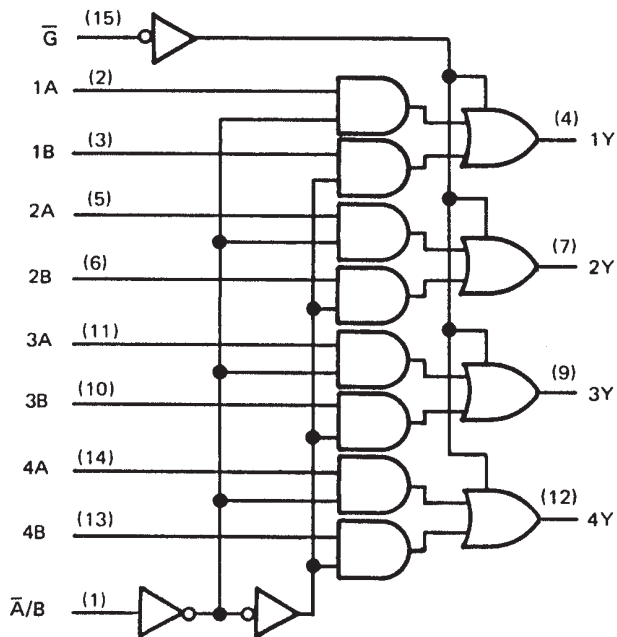
H = high level, L = low level, X = irrelevant,
Z = high impedance (off)

SN54LS257B, SN54LS258B, SN54S257, SN54S258
 SN74LS257B, SN74LS258B, SN74S257, SN74S258
 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

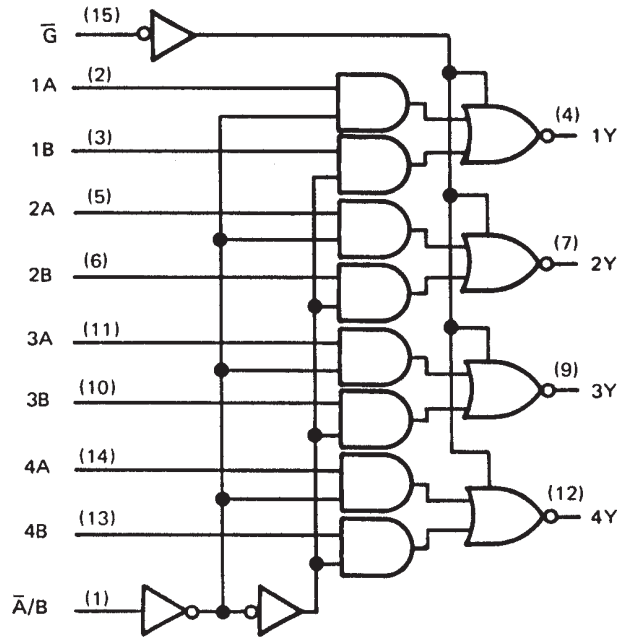
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logic diagrams (positive logic)

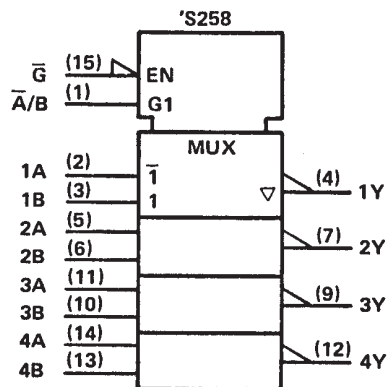
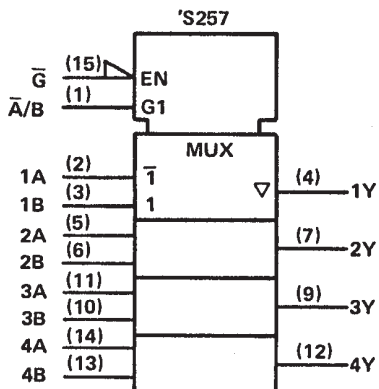
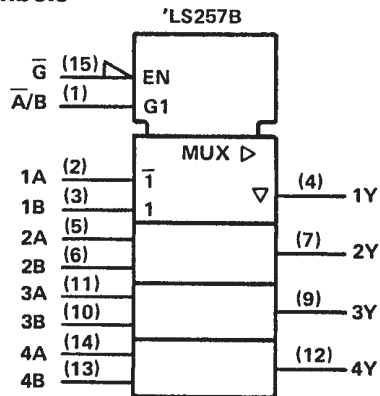
'LS257B, 'S257



'LS258B, 'S258



logic symbols†

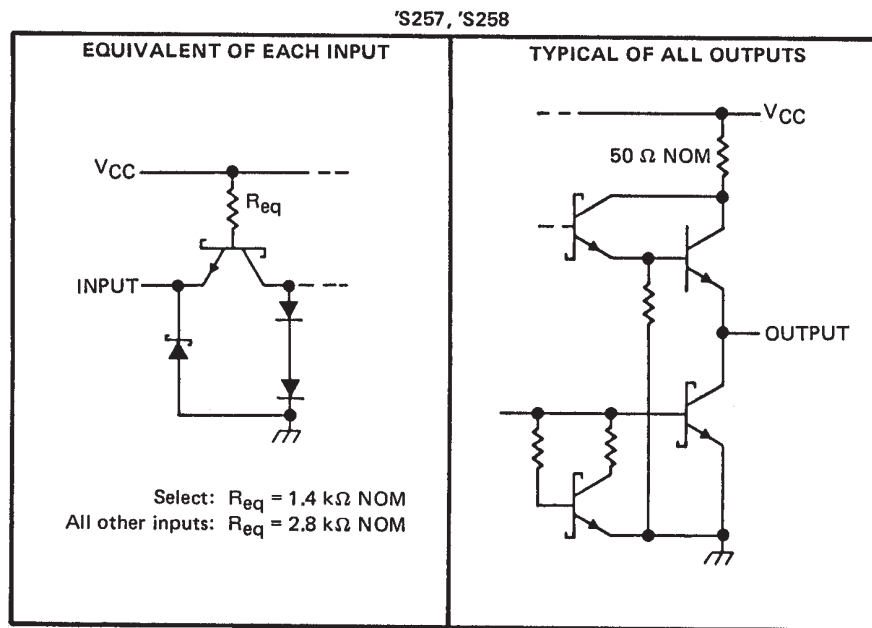


†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

SN54LS257B, SN54LS258B, SN54S257, SN54S258
 SN74LS257B, SN74LS258B, SN74S257, SN74S258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage: 'LS257B, 'LS258B Circuits	7 V
'S257, 'S258 Circuits	5.5 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS', SN54S' Circuits	-55°C to 125°C
SN74LS', SN74S' Circuits	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



**SN54LS257B, SN54LS258B, SN54S257, SN54S258
SN74LS257B, SN74LS258B, SN74S257, SN74S258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS**

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recommended operating conditions

	SN54LS'			SN74LS'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.7			0.8	V
I _{OH} High-level output current			-1			-2.6	mA
I _{OL} Low-level output current			12			24	mA
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS'			SN74LS'			UNIT	
		MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V _{IK}	V _{CC} = MIN, I _I = -18 mA			-1.5			-1.5	V	
V _{OH}	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX, I _{OH} = MAX	2.4	3.4		2.4	3.1		V	
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX, I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V	
						0.35	0.5		
I _{OZH}	V _{CC} = MAX, V _{IH} = 2 V, V _O = 2.7 V			20			20	µA	
I _{OZL}	V _{CC} = MAX, V _{IH} = 2 V, V _O = 0.4 V			-20			-20	µA	
I _I	V _{CC} = MAX, V _I = 7 V			0.1			0.1	mA	
I _{IH}	V _{CC} = MAX, V _I = 2.7 V			20			20	µA	
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			-0.4			-0.4	mA	
I _{OS} §	V _{CC} = MAX,	-30		-130	-30		-130	mA	
I _{CC}	All outputs high	V _{CC} = MAX, See Note 2		'LS257B	8	12	8	12	mA
	All outputs low				12	18	12	18	
	All outputs off				13	19	13	19	
	All outputs high				6	9	6	9	
	All outputs low				10	15	10	15	
	All outputs off				11	16	11	16	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

switching characteristics, V_{CC} = 5 V, T_A = 25°C, R_L = 667 Ω

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS257B			'LS258B			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t _{PLH}	Data	Any	C _L = 45 pF, See Note 3	8	13		7	12	ns	
t _{PHL}				10	15		11	17		
t _{PLH}	Select	Any		16	21		14	21	ns	
t _{PHL}				17	24		19	24		
t _{pZH}	Output Control	Any		15	30		15	30	ns	
t _{pZL}				19	30		20	30		
t _{PHZ}	Output Control	Any	C _L = 5 pF, See Note 3	18	30		18	30	ns	
t _{PLZ}			16	25		16	25			

¶ t_{PLH} = propagation delay time, low-to-high-level output

t_{PHL} = propagation delay time, high-to-low-level output

t_{pZH} = output enable time to high level

t_{pZL} = output enable time to low level

t_{PHZ} = output disable time from high level

t_{PLZ} = output disable time from low level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



SN54LS257B, SN54LS258B, SN54S257, SN54S258 SN74LS257B, SN74LS258B, SN74S257, SN74S258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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recommended operating conditions

	SN54S'			SN74S'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			-2			-6.5	mA
Low-level output current, I_{OL}			20			20	mA
Operating free-air temperature, T_A	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	'S257			'S258			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage		0.8			0.8			V
V_{IK}	Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$	-1.2			-1.2			V
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OH} = -1 \text{ mA}$	SN74S'			2.7			V
		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OH} = \text{MAX}$	SN54S'			2.4 3.4			
			SN74S'			2.4 3.2			
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 20 \text{ mA}$	0.5			0.5			V
I_{OZH}	Off-state output current, high-level voltage applied	$V_{CC} = \text{MAX}, V_{IH} = 2 \text{ V}, V_O = 2.4 \text{ V}$	50			50			μA
I_{OZL}	Off-state output current, low-level voltage applied	$V_{CC} = \text{MAX}, V_{IH} = 2 \text{ V}, V_O = 0.5 \text{ V}$	-50			-50			μA
I_I	Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$	1			1			mA
I_{IH}	High-level input current	S input	100			100			μA
		Any other	50			50			
I_{IL}	Low-level input current	S input	-4			-4			mA
		Any other	-2			-2			
I_{OS}	Short-circuit output current§	$V_{CC} = \text{MAX}$	-40 -100			-40 -100			mA
I_{CC}	Supply current	All outputs high	44 68			36 56			mA
		All outputs low	60 93			52 81			
		All outputs off	64 99			56 87			

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}, R_L = 280 \Omega$

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'S257			'S258			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_{PLH}	Data	Any	$C_L = 15 \text{ pF},$ See Note 3	5 7.5			4 6			ns
t_{PHL}				4.5 6.5			4 6			
t_{PLH}	Select	Any		8.5 15			8 12			ns
t_{PHL}				8.5 15			7.5 12			
t_{PZH}	Output	Any		13 19.5			13 19.5			ns
t_{PZL}	Control			14 21			14 21			
t_{PHZ}	Output	Any	5.5 8.5			5.5 8.5			ns	
t_{PLZ}	Control		9 14			9 14				

¶ f_{max} = Maximum clock frequency

t_{PLH} = propagation delay time, low-to-high-level output

t_{PHL} = propagation delay time, high-to-low-level output

t_{PZH} = output enable time to high level

t_{PZL} = output enable time to low level

t_{PHZ} = output disable time from high level

t_{PLZ} = output disable time from low level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-7603701VEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
5962-7603701VF A	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-7603701VF A	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
7603701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
7603701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
7603701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
7603701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
76038012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
76038012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
7603801EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
7603801EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
7603801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
7603801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
8002301EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
8002301EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
8002301FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
8002301FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN74LS257BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS257BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS257BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS257BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS257BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS257BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS257BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS257BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS258BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS258BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS258BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS258BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS258BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS258BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS258BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S257N	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S257N	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S257N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S257N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S257NE4	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S257NE4	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S258N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S258N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SNJ54LS257BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS257BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54LS257BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS257BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS258BFBK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS258BFBK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS258BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS258BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54S257FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S257FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54S257W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54S257W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54S258FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S258FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54S258W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54S258W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS257BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS257BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS258BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS258BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS257BDR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS257BNSR	SO	NS	16	2000	346.0	346.0	33.0
SN74LS258BDR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS258BNSR	SO	NS	16	2000	346.0	346.0	33.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

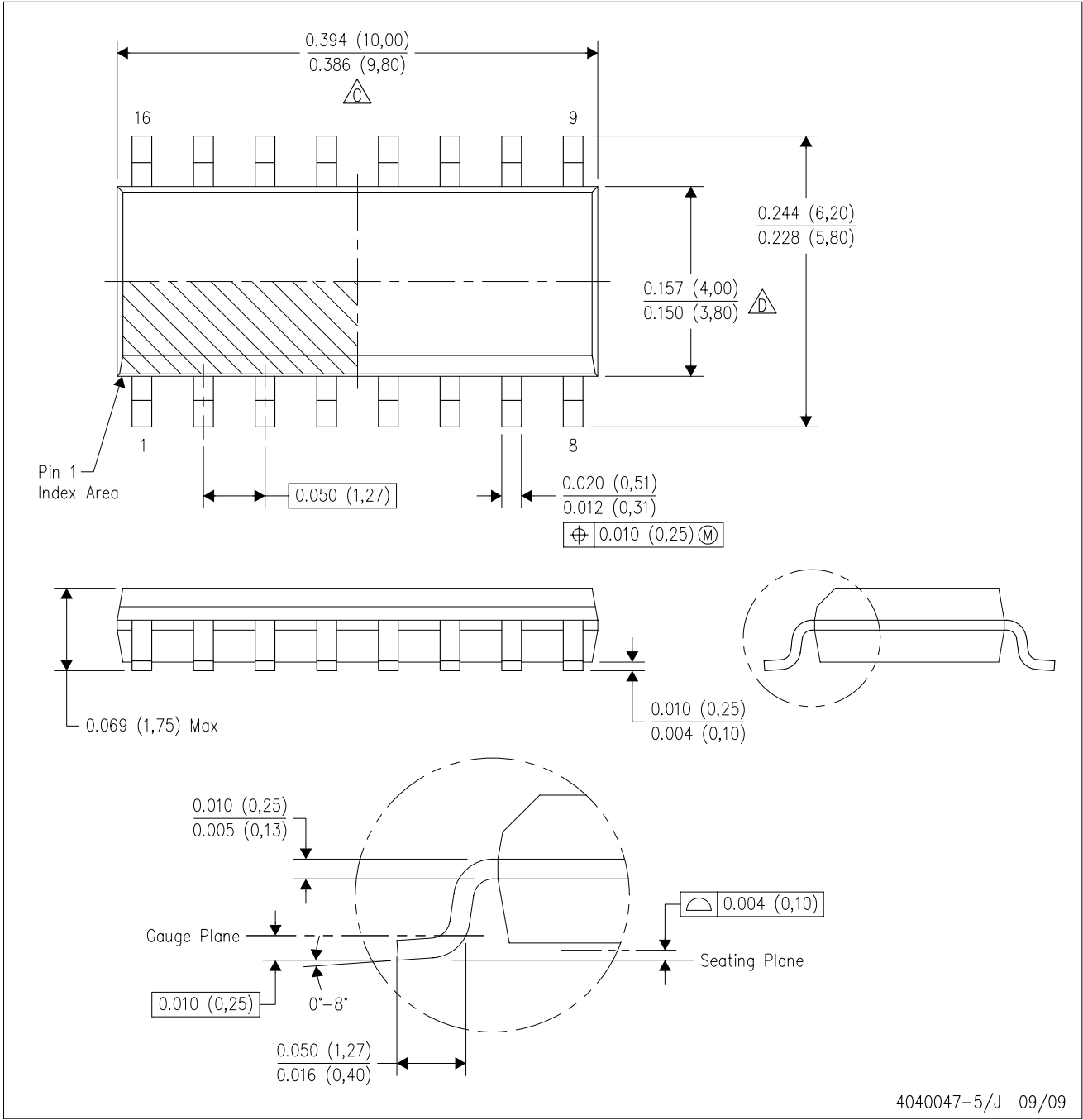
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-5/J 09/09

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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